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BGA TWTK-BGAP-24 plating kit

Product ID: 1873

Price: **11.00 EUR**

Product weight: **0.01 kg**

Description:

BGA TWTK-BGAP-24 plating kit it's a 24 set matrix for that's needed tool when you have to exchange BGA parts of your phone. It's supports Motorola and Smasung chips as V600 UEM, E680 Flash, V66 Flash, A760 CPU, E680 CPU, V66/V60 CPU, E680 Flash Fan, 998/V66/V70 IC, V70, L2000/998+ Flash, L2000/998 MF/UEM, T2688 MF, 923/998 or T18/T28 IC, V70 MF, T191/998 UEM, V300 CPU, V300 Flash, V300 UEM, A760 RAM, 998 BM, 928 CPU, A760 UEM and A70 Flash.

Click to link for bigger photo - [LINK](#)

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